

IN THE CLAIMS:

This Listing of Claims will replace all prior versions, and listings, of claims in the subject Patent Application:

Listing of Claims:

1. (Currently amended) A heat sink module, comprising:

a base; and,

a heat dissipation pad being flexible and biased to a cambered shape,
the heat dissipation pad having a fixing portion coupled to the base and a flexible
portion extending deflectively therefrom to terminate at a free end, wherein the
flexible portion of the heat dissipation pad deflectable to a substantially flat
configuration when captured ~~being~~ between a heat conducting plate and a CPU.

2. (Currently amended) The heat sink module according to claim 1, ~~further~~
~~comprises:~~ wherein the a base includes ~~with~~ a fixing device, the fixing device
fixing ~~fixes~~ the heat sink module in a portable electronic device, wherein one side
of the heat dissipation pad is positioned to one side of the base.

3. (Original) The heat sink module according to claim 2, wherein the
portable electronic device is a notebook computer.

4. (Original) The heat sink module according to claim 2, wherein the portable electronic device is a tablet PC.

5. (Original) The heat sink module according to claim 2, wherein the portable electronic device is a personal digital assistant (PDA).

6. (Original) The heat sink module according to claim 1, wherein the heat conducting plate is fixed to the base and against the heat dissipation pad tightly when the heat sink module installed in a portable electronic device.

7. (Original) The heat sink module according to claim 1, further comprises:

a heat pipe, which one end connects the heat conducting plate to bring away heat accumulated at the heat conducting plate.

8. (Currently amended) The heat sink module according to claim 7, further comprising:

a plurality of heat dissipation fins connected to another end of the

heat pipe.

9. (Currently amended) The heat sink module according to claim 8, further comprising:

a fan is provided beside the plurality of heat dissipation fins.

10-11. (Canceled).

12. (Original) The heat sink module according to claim 1, wherein the heat dissipation pad is in a shape of a plate.

13. (Currently amended) The heat sink module according to claim 14, wherein the flexible portion of the heat dissipation pad is in a shape of a cambered plate.

14. (Original) The heat sink module according to claim 1, wherein the heat dissipation pad is made of heat dissipation material.

15. (Original) The heat sink module according to claim 1, wherein heat dissipation paste is applied between a heat conducting plate and the heat dissipation pad.

16. (New) A heat sink module for a heat generating device comprising:

a frame for supporting the heat generating device;

a base detachably coupled to the frame;

a heat dissipation pad releasably captured against the heat generating device by the base when the base is coupled to the frame, the heat dissipation pad having a fixing portion coupled to the base and a flexible portion extending deflectively therefrom to terminate at a free end, the flexible portion being biased to a cambered shape, the flexible portion being deflectable to a substantially flat configuration when captured by the base against the heat generating device.

17. (New) The heat sink module as recited in Claim 16, wherein the base includes a heat conducting plate, the flexible portion extending substantially over the heat conducting plate.